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LITE-ON DCC

RELEASE

BNS-OD-FC001/A4

LITE-ON Technology Corp. / Optoelectronics

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1. DESCRIPTION

1.1 Features

- Isolation voltage between input and output V_{iso}: 5,000V_{rms}
- 6pin DIP zero-cross photocoupler, triac driver output
- High repetitive peak off-state voltage VDRM : Min. 600V
- High critical rate of rise of off-state voltage(dV/dt : MIN. 1000V / µs)
- Dual-in-line package: MOC3061 / MOC3062 / MOC3063
- Wide lead spacing package: MOC3061M / MOC3062M / MOC3063M
- Surface mounting package : MOC3061S / MOC3062S / MOC3063S
- Tape and reel packaging: MOC3061S-TA / MOC3062S-TA1 / MOC3063S-TA1 MOC3061S-TA1 / MOC3062S-TA1 / MOC3063S-TA1
- Safety approval

UL 1577, Cert. No.E113898 CSA CA5A, Cert. No. 1020087 (CA 91533-1) FIMKO EN/IEC 60950-1, EN/IEC 60065; Cert. No.NCS/FI 24426 M3 VDE DIN EN60747-5-2, Cert. No. 40015248 CQC GB4943.1-2011/ GB8898-2011

- RoHS Compliance
 - All materials be used in device are followed EU RoHS directive (No.2002/95/EC).
- MSL class1
- Halogen free option

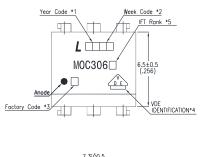
1.2 Applications

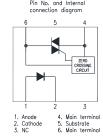
- AC Motor Drives
- AC Motor Starters
- E.M. Contactors
- Lighting Controls
- Solenoid/Valve Controls
- Solid State Relays
- Static Power Switches
- Temperature Controls

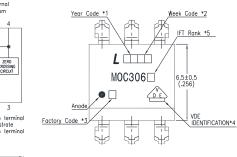


2. PACKAGE DIMENSIONS

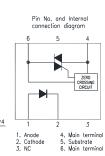
2.1 MOC306X

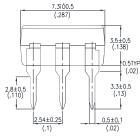


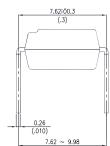


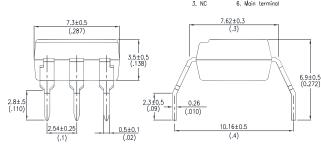


2.2 MOC306XM

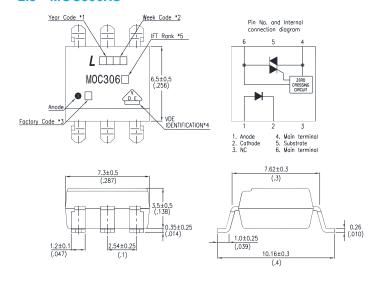








2.3 MOC306XS



Notes:

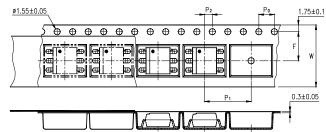
- 1. 2-digit year code, example : 2016 = 16
- 2. 2-digit work week ranging from '01' to '53'
- Factory identification mark shall be marked (W: China-CZ, Y: Thailand)
- 4. VDE option
- 5. I_{FT} rank
- * Dimensions are in Millimeters and (Inches).



3. TAPING DIMENSIONS

3.1 MOC306XS-TA

3.2 MOC306XS-TA1



Description	Symbol	Dimension in mm (inch)			
Tape wide	W	16±0.3 (0.63)			
Pitch of sprocket holes	P ₀	4±0.1 (0.15)			
Distance of compartment	F	7.5±0.1 (0.295)			
Distance of compartment	P ₂	2±0.1 (0.079)			
Distance of compartment to compartment	P ₁	12±0.1 (0.472)			

3.3 Quantities Per Reel

Package Type	MOC306XS series
Quantities (pcs)	1000



4. RATING AND CHARACTERISTICS

4.1 Absolute Maximum Ratings at Ta=25℃

	Parameter	Symbol	Rating	Unit	
	Forward Current	I _F	50	mA	
land	Reverse Voltage	V_R	6	V	
Input	Junction Temperature	TJ	125	°C	
	Power Dissipation	Р	120	mW	
	Off-State Output Terminal Voltage	V_{DRM}	600	V	
	On-State RMS Current	$I_{D(RMS)}$	100	mA	
Output	Peak Repetitive Surge Current	etitive Surge Current		А	
Odiput	(PW=1ms, 120pps)	TISM	1	Α	
	Junction Temperature	ΤJ	125	°C	
	Output Power Dissipation	Pc	300	mW	
	Total Power Dissipation	P_{tot}	330	mW	
1.	Isolation Voltage	V_{iso}	5000	V_{rms}	
	Operating Temperature	T_{opr}	-40 ~ +110	°C	
	Storage Temperature	T_{stg}	-55 ~ +150	°C	
2.	Soldering Temperature	T _{sol}	260	°C	

1. AC For 1 Minute, R.H. = $40 \sim 60\%$

Isolation voltage shall be measured using the following method.

- (1) Short between anode and cathode on the primary side and between collector and emitter on the secondary side.
- (2) The isolation voltage tester with zero-cross circuit shall be used.
- (3) The waveform of applied voltage shall be a sine wave.
- 2. For 10 Seconds



4.2 Recommended Operating Conditions (Note)

Character	istics	Symbol	Min.	Тур.	Max.	Unit
Supply Voltage		Vac	-	-	240	Vac
	MOC3061	l _F	22.5	25	30	mA
Forward Current	MOC3062		15	20	30	mA
	MOC3063		7.5	10	30	mA
Operating Temperature		T_{opr}	-25	-	85	°C

Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device.

Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.



4.3 Electrical Optical Characteristics at Ta=25℃

Parameter		Symb	Min.	Тур.	Max.	Unit	Test Condition		
	Forward Voltage			V_{F}	_	1.2	1.4	٧	I _F =20mA
Input Reverse Current		Reverse Current	everse Current		_	0.05	10	μΑ	V _R =6V
	Peak Blocking Current, Either 1 Direction		I _{DRM}	_	_	500	nA	V _{DRM} = 600V	
Output	Peak On-State Voltage, Either Direction		V_{TM}	_	_	3.0	V	I _{TM} =100 mA Peak	
Critical rate 2 Voltage			tical rate of Rise of Off-State		1000	_	_	V/μs	Vin=240Vrms
Couple	Led Trigger Current,	MOC3061		_	_	15	mA		
		Current Required to Latch Output, Either	MOC3062	I _{FT}	_	—	10	mA	Main Terminal Voltage = 3V
	Direction	MOC3063		_	_	5	mA		
	Holding Current, Either Direction		l _Η	_	200	_	μΑ		
ZERO CROSSING		Inhibit Voltage		Vinh	_	5	20	Volts	I _F =Rated I _{FT} , MT1-MT2 Voltage above which device will not trigger.
	Leakage in Inhibited State		I _{DRM2}	_	_	500	μΑ	I_F = Rated I_{FT} , Rated V_{DRM} , Off State	

^{*1.} Test voltage must be applied within dv/dt rating.

^{*2.} This is static dv/dt. Commutating dv/dt is a function of the load-driving thyristor(s) only.



CHARACTERISTICS CURVES (TYPICAL PERFORMANCE)

Fig.1 Forward Current vs.

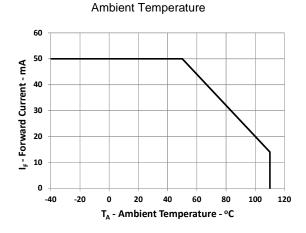


Fig.2 On-state Current vs. Ambient **Temperature**

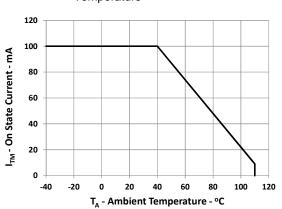


Fig.3 Normalized Trigger Current

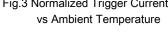
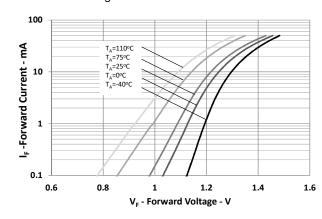


Fig.4 Forward Current vs. Forward Voltage



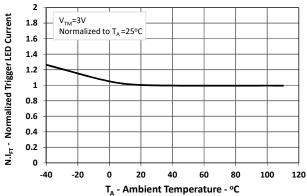


Fig.5 Normalized On-state Voltage vs Ambient Temperature

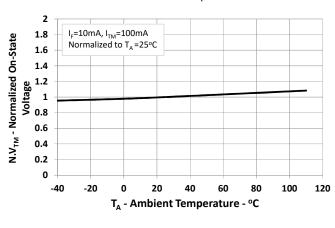
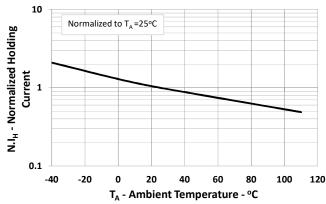
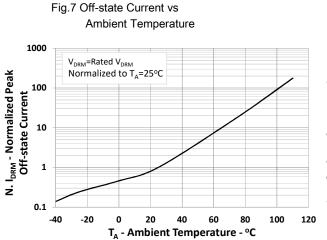


Fig.6 Normalized Holding Current vs Ambient Temperature







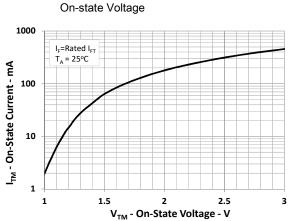
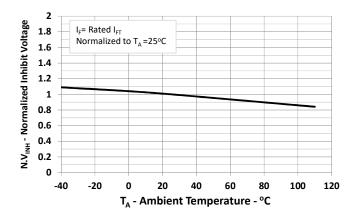


Fig.8 On-state Current vs

Fig.9 Inhibit Voltage vs
Ambient Temperature



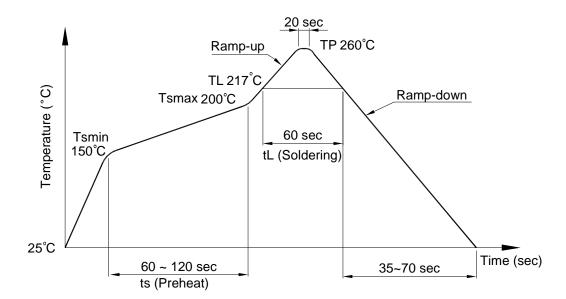


6. TEMPERATURE PROFILE OF SOLDERING

6.1 IR Reflow soldering (JEDEC-STD-020E compliant)

One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three times.

Profile item	Conditions				
Preheat					
- Temperature Min (T _{Smin})	150°C				
- Temperature Max (T _{Smax})	200°C				
- Time (min to max) (ts)	90±30 sec				
Soldering zone					
- Temperature (T _L)	217°C				
- Time (t _L)	60 sec				
Peak Temperature (T _P)	260°C				
Ramp-up rate	3°C / sec max.				
Ramp-down rate	3~6°C / sec				





6.2 Wave soldering (JEDEC22A111 compliant)

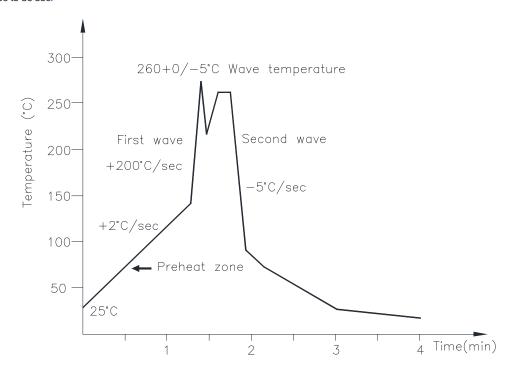
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C

Time: 10 sec.

Preheat temperature:25 to 140°C

Preheat time: 30 to 80 sec.



6.3 Hand soldering by soldering iron

Allow single lead soldering in every single process. One time soldering is recommended.

Temperature: 380+0/-5°C

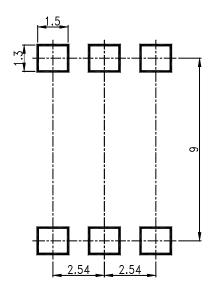
Time: 3 sec max.





7. RRECOMMENDED FOOT PRINT PATTERNS (MOUNT PAD)

Unit: mm





8. NAMING RULE

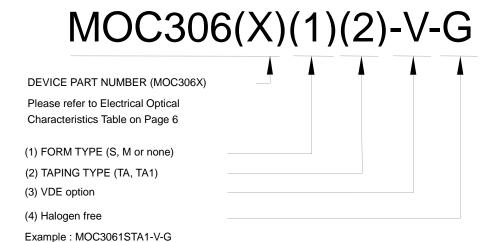


DEVICE PART NUMBER (MOC306X)

Please refer to Electrical Optical Characteristics Table on Page 6

- (1) FORM TYPE (S, M or none)
- (2) TAPING TYPE (TA, TA1)
- (3) Halogen free

Example: MOC3061S-TA1-G



9. NOTES

- LiteOn is continually improving the quality, reliability, function or design and LiteOn reserves the right to make changes without further notices.
- The products shown in this publication are designed for the general use in electronic applications such as office automation equipment, communications devices, audio/visual equipment, electrical application and instrumentation.
- For equipment/devices where high reliability or safety is required, such as space applications, nuclear power control equipment, medical equipment, etc, please contact our sales representatives.
- When requiring a device for any "specific" application, please contact our sales in advice.
- If there are any questions about the contents of this publication, please contact us at your convenience.
- The contents described herein are subject to change without prior notice.
- Immerge unit's body in solder paste is not recommended.

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Part No.:MOC306X series BNC-OD-FC002/A4